



DATE: 23rd February, 2016

PCN #: 2181 REV 01

PCN Title: Conversion to Copper Bond Wire, Additional A/T site, and/or Additional Wafer Source with Smaller Die Size on Selected Discrete Products

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE

PCN-2181 REV 01

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
23 rd February, 2016	22 nd May, 2016	Discrete Semiconductors	Bond Wire Material / Wafer FAB Material / Additional Assembly & Test Site	2181
TITLE				
Conversion to Copper Bond Wire, Additional A/T site, and/or Additional Wafer Source with Smaller Die Size on Selected Discrete Products				
DESCRIPTION OF CHANGE				
<p>This PCN is being issued to notify customers that Diodes has qualified Copper bond wire for the selected Discrete products listed in this PCN. In order to accommodate the Copper bond wire, the top metal composition and/or top metal thickness of the wafer has been modified. Diodes Incorporated has also qualified an additional wafer source with smaller die size, Diodes internal FabTech Inc. (KFAB) or external Phenitec Semiconductor (*), and qualified "Diodes Technology (Chengdu) Company Limited" (CAT) as an additional Assembly & Test Site (A/T Site) for the selected Discrete products.</p> <p>Full electrical characterization and high reliability testing has been completed on representative part numbers built using Copper bond wire, alternative wafer source and/or additional A/T site to ensure no change to device functionality or electrical specifications in the datasheet.</p> <p>There will be no change to the Form, Fit, or Function of affected products.</p> <p>REV 01: Add part numbers: MMBT2222A-13-F, MMBT2222A-7-F, MMST2222A-7-F – Change: Additional Wafer Source with Smaller Die Size (Table 4)</p>				
IMPACT				
There is no change in datasheet parameters and product performance.				
PRODUCTS AFFECTED				
Please refer to Table 1 for Cu bond wire conversion Please refer to Table 2 for Cu bond wire conversion and additional wafer source with smaller die size Please refer to Table 3 for additional A/T site and additional wafer source with smaller die size Please refer to Table 4 for additional wafer source with smaller die size				
WEB LINKS				
Manufacturer's Notice:	http://www.diodes.com/quality/pcns			
For More Information Contact:	http://www.diodes.com/contacts			
Data Sheet:	http://www.diodes.com/products			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				

Table 1 - Cu Bond Wire Conversion				
DCX114EU-7-F	DDC114TU-7-F	DDTA144WE-7-F	DCX114EH-7	ZUMT718TA
DCX114TU-7-F	DDC114YU-7-F	DDTC113ZE-7-F	DDA114EH-7	ZUMT720TA
DCX114YU-7-F	DDC123JU-7-F	DDTC114EE-7-F	DDA114TH-7	BC817-40W-7
DCX123JU-7-F	DDC124EU-7-F	DDTC114GE-7-F	DDA114YH-7	MMST5401-7-F
DCX124EU-7-F	DDC143TU-7-F	DDTC114YE-7-F	DDA124EH-7	MMST5551-7-F
DCX143EU-7-F	DDC144EU-7-F	DDTC115EE-7-F	DDC114EH-7	MMST6427-7-F
DCX143TU-7-F	DDC144NS-7	DDTC122LE-7-F	DDC114YH-7	MMSTA13-7-F
DCX144EU-7-F	DDC144TU-7	DDTC123JE-7-F	DDC123JH-7	MMSTA14-7-F
DDA113TU-7-F	DDTA113TE-7-F	DDTC123YE-7-F	DDC142TH-7	MMSTA42-7-F
DDA114EU-7-F	DDTA113ZE-7-F	DDTC124EE-7-F	DDC143TH-7	MMSTA55-7-F
DDA114TU-7-F	DDTA114EE-7-F	DDTC124XE-7-F	ZUMT491TA	MMSTA56-7-F
DDA114YU-7-F	DDTA114WE-7-F	DDTC143EE-7-F	ZUMT591TA	MMSTA92-7-F
DDA123JU-7-F	DDTA123JE-7-F	DDTC143TE-7-F	ZUMT617TA	2DB1689-7
DDA143TU-7-F	DDTA123YE-7-F	DDTC143XE-7-F	ZUMT618TA	2DB1694-7
DDA144EU-7-F	DDTA143EE-7-F	DDTC143ZE-7-F	ZUMT619TA	2DD2652-7
DDC113TU-7-F	DDTA143TE-7-F	DDTC144EE-7-F	ZUMT619TC	2DD2656-7
DDC114EU-7-F	DDTA144EE-7-F	DDTC144WE-7-F	ZUMT717TA	T6V0S5-7

Table 2 - Cu Bond Wire Conversion and Additional Wafer Source with Smaller Dies Size				
MMBT2907AT-7-F	MMDT2222V-7	MMDT2907V-7	MMDT3906VC-7	MMBT3906T-13-F
MMBT2222A-7-G	DLP05LC-7-F*			

* Phenitec Semiconductor as an additional wafer source

Table 3 - Additional A/T site and Additional Wafer Source with Smaller Die Size				
MMDT4124-7-F	MMDT3946-7-F	MMBT4126-7-F	MMBT3904-13-F	DMMT3904W-7-F
MMDT3906-7-F	MMDT4146-7-F	MMDT3904-7-F	MMBT3906-13-F	DMMT3906W-7-F
MMDT4126-7-F	MMBT4124-7-F	MMDT2907A-7-F		

Table 4 - Additional Wafer Source with Smaller Die Size				
MMBT2222AT-7-F	MMDT3904VC-7	MMST3904-7-F	MMST4126-7-F	MMBT2907A-13-F
MMBT3904T-7-F	MMDT2222A-7-F	MMST3906-7-F	MMBT3904-7-F	MMBT2907A-7-F
MMBT3906T-7-F	MMDT2227-7-F	MMST4124-7-F	MMBT3906-7-F	MMDT2227M-7
MMDT3904V-7	MMST2907A-7-F			